

Abstract

An electronic device package comprises a substrate, a die, and a material having a Young's modulus of between about .1 megapascals and about 20 megapascals (at a solder reflow temperature) for attaching the die to the substrate. In one embodiment, the

- 5 package utilizes a material having a Young's modulus of between about .1 megapascals and about 20 megapascals (at a solder reflow temperature) for attaching the die to the substrate. In an alternate embodiment, the package utilizes a material having a coefficient of thermal expansion α_2 of less than about 400 (four-hundred) ppm (parts per million)/°C for attaching the die to the substrate. In another alternate embodiment, the package
- 10 utilizes a rigid material for attaching the die to the substrate.

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